

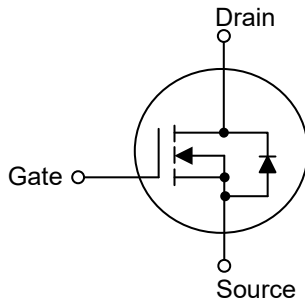
**02N40-TA****Power MOSFET****0.2A, 400V N-CHANNEL
POWER MOSFET****DESCRIPTION**

The UTC **02N40-TA** is a high voltage power MOSFET and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristics. This power MOSFET is usually used at high speed switching applications in power supplies, PWM motor controls, high efficient DC to DC converters and bridge circuits.

FEATURES

* $R_{DS(ON)} \leq 14 \Omega$ @ $V_{GS}=10V$, $I_D=0.1A$

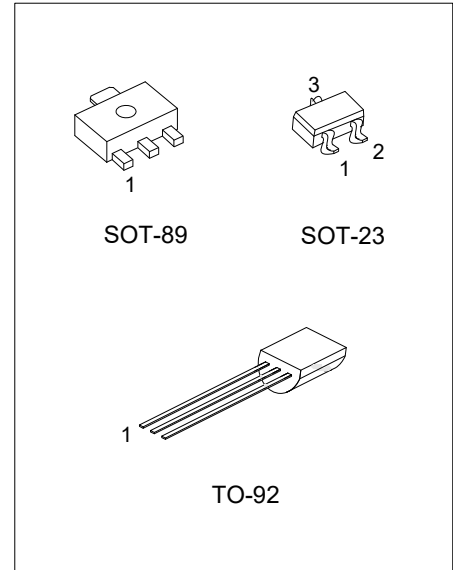
* High breakdown voltage

SYMBOL**ORDERING INFORMATION**

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
02N40L-TA-AB3-R	02N40G-TA-AB3-R	SOT-89	G	D	S	Tape Reel
02N40L-TA-AE3-R	02N40G-TA-AE3-R	SOT-23	G	S	D	Tape Reel
02N40L-TA-T92-B	02N40G-TA-T92-B	TO-92	G	D	S	Tape Box
02N40L-TA-T92-K	02N40G-TA-T92-K	TO-92	G	D	S	Bulk

Note: Pin Assignment: G: Gate D: Drain S: Source

02N40G-TA-AB3-R	(1)Packing Type	(1) R: Tape Reel, B: Tape Box, K: Bulk
	(2)Package Type	(2) AB3: SOT-89, AE3: SOT-23, T92: TO-92
	(3)Version Code	(3) Version TA
	(4)Green Package	(4) G: Halogen Free and Lead Free, L: Lead Free



MARKING

PACKAGE	MARKING
SOT-89	TA 02N40 1 Date Code → Version Code → L: Lead Free G: Halogen Free
SOT-23	02N40
TO-92	UTC 02N40 TA Version Code → L: Lead Free G: Halogen Free → Date Code 1

■ **ABSOLUTE MAXIMUM RATINGS** ($T_C=25^{\circ}\text{C}$, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DS}	400	V
Gate-Source Voltage		V_{GS}	± 30	V
Drain Current	Continuous	I_D	0.2	A
	Pulsed	I_{DM}	1.2	A
Peak Diode Recovery dv/dt (Note 3)		dv/dt	3.3	V/ns
Power Dissipation	SOT-89	P_D	1.5	W
	SOT-23		0.4	W
	TO-92		1	W
Junction Temperature		T_J	150	$^{\circ}\text{C}$
Storage Temperature Range		T_{STG}	$-55 \sim +150$	$^{\circ}\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature.

3. $I_{SD} \leq 0.2\text{A}$, $di/dt \leq 200\text{A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, $T_J \leq T_{JMAX}$, $T_J = 25^{\circ}\text{C}$.

■ **THERMAL DATA**

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient	SOT-89	θ_{JA}	130	$^{\circ}\text{C}/\text{W}$
	SOT-23		325	$^{\circ}\text{C}/\text{W}$
	TO-92		160 (Note)	$^{\circ}\text{C}/\text{W}$
Junction to Case	SOT-89	θ_{JC}	83.3	$^{\circ}\text{C}/\text{W}$
	SOT-23		312	$^{\circ}\text{C}/\text{W}$
	TO-92		125 (Note)	$^{\circ}\text{C}/\text{W}$

Note: Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

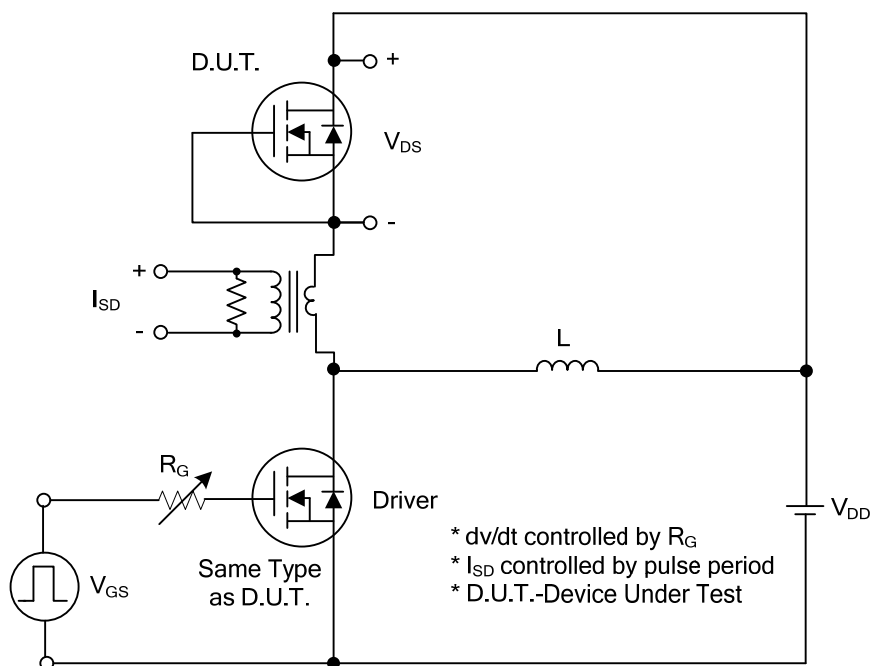
■ **ELECTRICAL CHARACTERISTICS** ($T_A=25^\circ\text{C}$, unless otherwise specified)

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV _{DSS}	I _D =250μA, V _{GS} =0V	400			V
Drain-Source Leakage Current		I _{DSS}	V _{DS} =400V, V _{GS} =0V			10	μA
Gate-Source Leakage Current	Forward	I _{GSS}	V _{GS} =+30V, V _{DS} =0V			+100	nA
	Reverse		V _{GS} =-30V, V _{DS} =0V			-100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage		V _{GS(TH)}	V _{DS} =V _{GS} , I _D =250μA	2.0		4.0	V
Static Drain-Source On-State Resistance		R _{DS(ON)}	V _{GS} =10V, I _D =0.1A			14	Ω
DYNAMIC PARAMETERS							
Input Capacitance		C _{ISS}	V _{GS} =0V, V _{DS} =25V, f=1.0MHz		59		pF
Output Capacitance		C _{OSS}			13		pF
Reverse Transfer Capacitance		C _{RSS}			2.2		pF
SWITCHING PARAMETERS							
Total Gate Charge		Q _G	V _{DS} =320V, V _{GS} =10V, I _D =0.2A (Note1,2)		8		nC
Gate to Source Charge		Q _{GS}			1		nC
Gate to Drain Charge		Q _{GD}			3		nC
Turn-ON Delay Time		t _{D(ON)}	V _{DS} =100V, V _{GS} =10V, I _D =0.2A, R _G =25Ω (Note1,2)		4.2		ns
Rise Time		t _R			17		ns
Turn-OFF Delay Time		t _{D(OFF)}			20		ns
Fall-Time		t _F			98		ns
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS							
Maximum Body-Diode Continuous Current		I _S				0.2	A
Maximum Body-Diode Pulsed Current		I _{SM}				1.2	A
Drain-Source Diode Forward Voltage		V _{SD}	I _S =0.2A, V _{GS} =0V			1.4	V
Reverse Recovery Time		t _{rr}	V _{GS} =0V, I _S =0.2A, di/dt=100A/μs		77		ns
Reverse Recovery Charge		Q _{rr}			92		nC

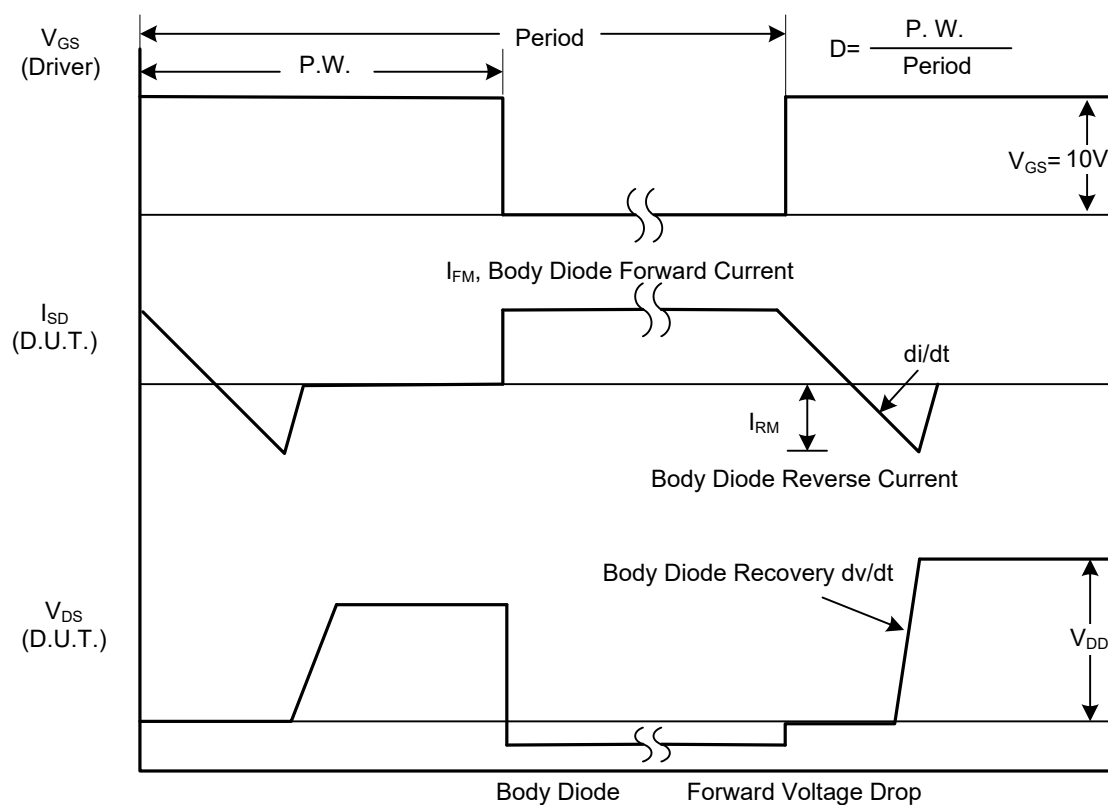
Notes: 1. Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$.

2. Essentially independent of operating temperature typical characteristics.

■ TEST CIRCUITS AND WAVEFORMS

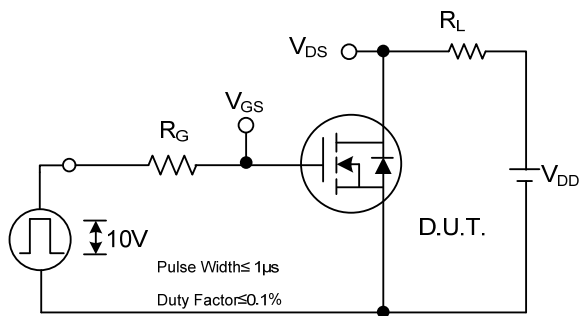


Peak Diode Recovery dv/dt Test Circuit

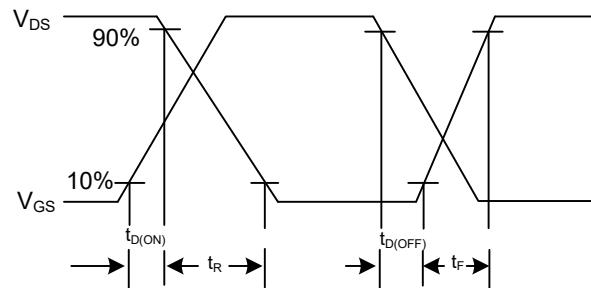


Peak Diode Recovery dv/dt Waveforms

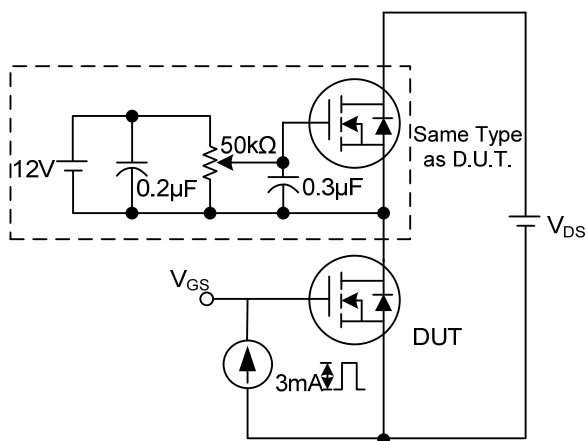
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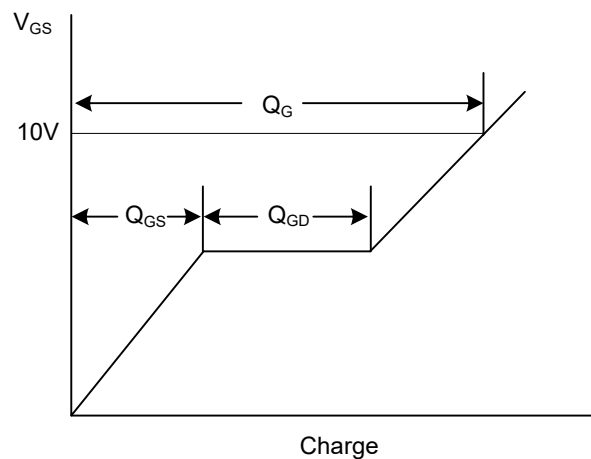
Switching Test Circuit



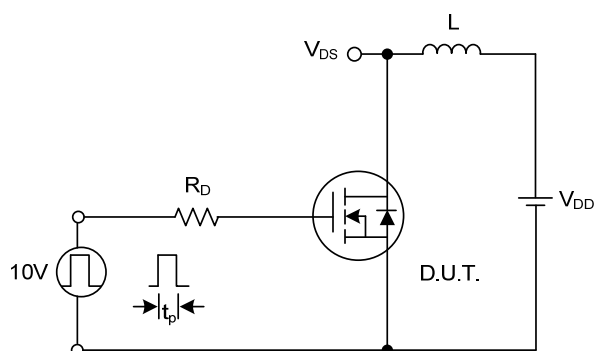
Switching Waveforms



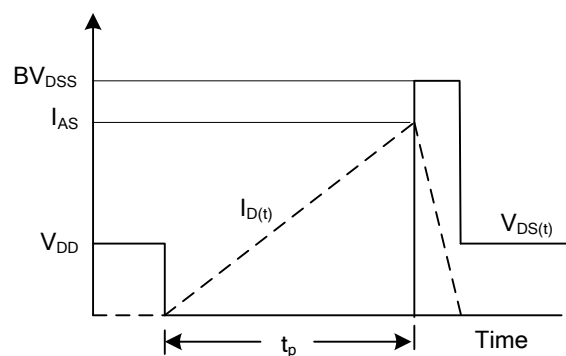
Gate Charge Test Circuit



Gate Charge Waveform

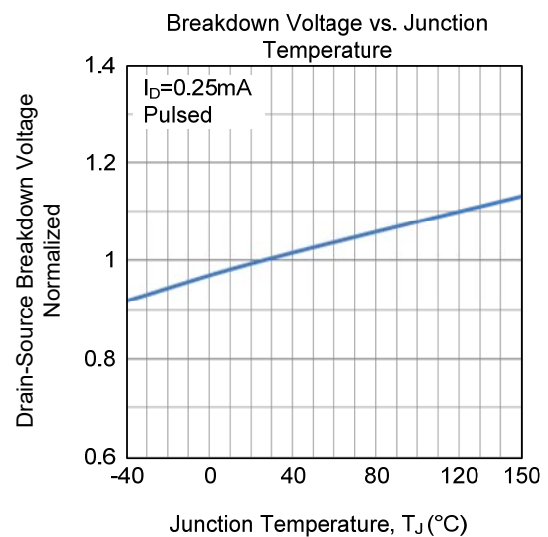
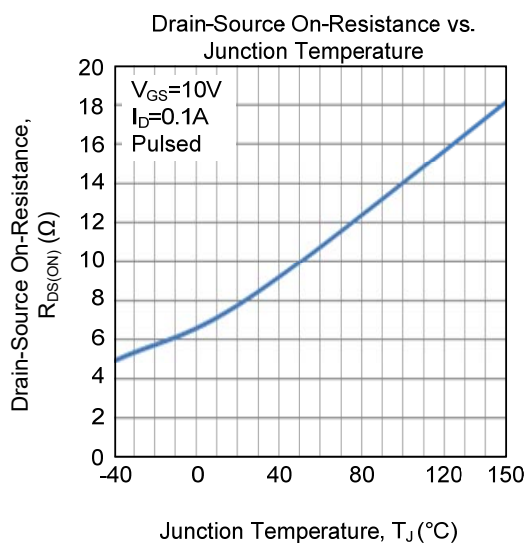
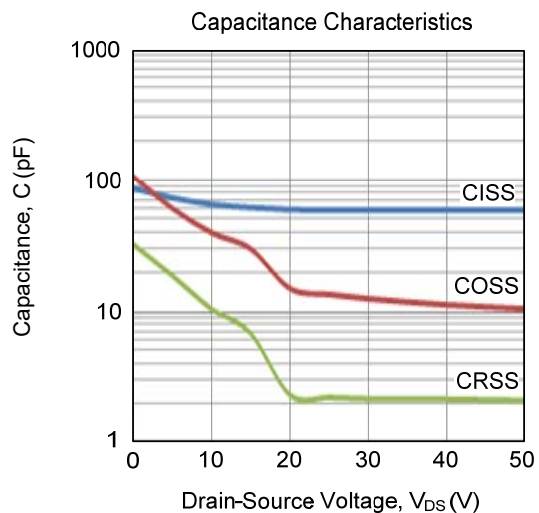
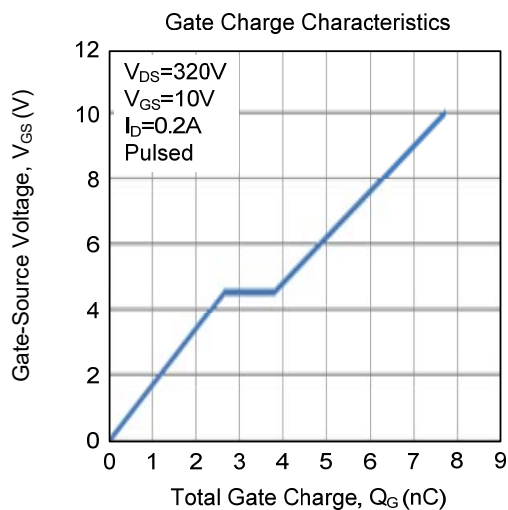
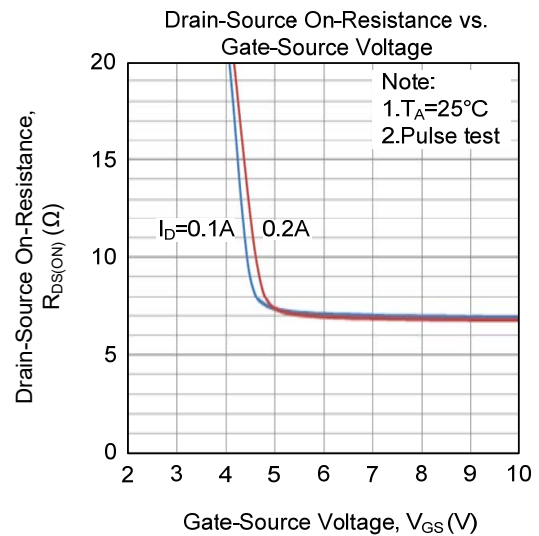
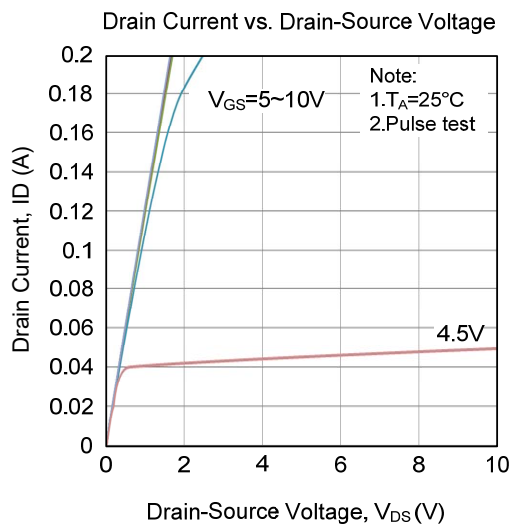


Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms

■ TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS (Cont.)

